

<https://indico.bnl.gov/event/16766/>



# Update on the Sensor Front

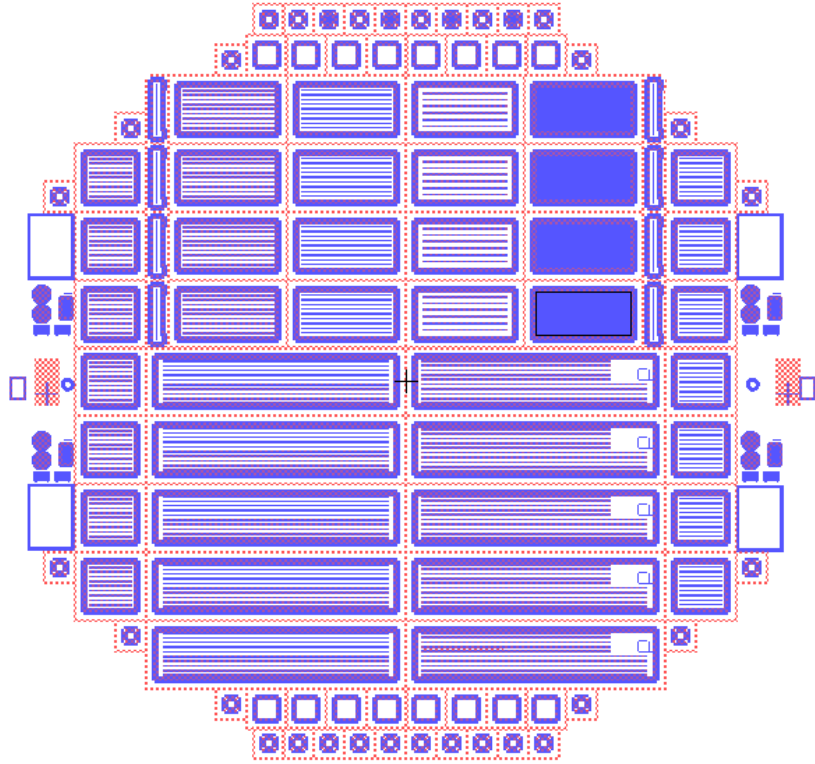
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## Layout #1

Metal (and GLASS) modified, mask produced and should be at BNL today/tomorrow.  
Litho ready to go, 2 wafers out by this week (next week passivation)



multiplicity	mm x mm	Pitch (um)	Gap (um)
7	5x5	500	400
7	5x5	500	450
4	5x10	500	400
4	5x10	500	450
4	5x10	700	600
4	5x10	Zig Zag	
5	5x25	500	400/450
5	5x25	500	400 (l=2 or 2.5cm)

2+2 wafers in  
fabrication (2 50um + 2  
20um)

Plan:

- Test (on a sample basis) the two wafers, then adjust gain dose and send out the other two.
- Plan to do SIMS to tune TCAD simulations



## Layout #2

Starting wafers: 50, 30, 20 um thick substrates

EICROC bump-bond compatible

Metal not designed yet,  
but lithos can start with:

- 1- JTE
- 2- Nresistive
- 3- gain
- 4- contacts

+ test structures

2cm x 0.5cm

0.5cm x 0.5cm

0.2cm x 0.2cm  
Compatible with EICROC

